

PCN Number:	20151214002		PCN Date:	12/17/2015																						
Title:	Add Cu as Alternative Wire Base Metal for Selected Device(s)																									
Customer Contact:	PCN Manager	Dept:	Quality Services																							
Proposed 1st Ship Date:	03/17/2016		Estimated Sample Availability:	Date provided at sample request																						
Change Type:																										
<input type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Design	<input type="checkbox"/>	Wafer Bump Site																					
<input checked="" type="checkbox"/>	Assembly Process	<input type="checkbox"/>	Data Sheet	<input type="checkbox"/>	Wafer Bump Material																					
<input checked="" type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change	<input type="checkbox"/>	Wafer Bump Process																					
<input type="checkbox"/>	Mechanical Specification	<input type="checkbox"/>	Test Site	<input type="checkbox"/>	Wafer Fab Site																					
<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process	<input type="checkbox"/>	Wafer Fab Materials																					
				<input type="checkbox"/>	Wafer Fab Process																					
PCN Details																										
Description of Change:																										
Texas Instruments is pleased to announce the qualification of Cu as an additional bond wire option for selected devices listed in "Product affected" section below. Devices will remain in current assembly facilities and there will be no other piece part changes:																										
	<table border="1"> <thead> <tr> <th>Pkg Family</th> <th>Current Wire</th> <th>Additional Wire</th> </tr> </thead> <tbody> <tr> <td>SOIC</td> <td>Au, 0.9 or 1.0 mils</td> <td>Cu, 0.96 mils</td> </tr> <tr> <td>SOT</td> <td>Au, 0.6, 0.9 or 1.0 mils</td> <td>Cu, 0.96 or 1.0 mils</td> </tr> <tr> <td>TSSOP</td> <td>Au, 1.0 mils</td> <td>Cu, 0.96 mils</td> </tr> <tr> <td>VSSOP</td> <td>Au, 1.0 or 1.3 mils</td> <td>Cu, 0.96 or 1.3 mils</td> </tr> <tr> <td>WQFN</td> <td>Au, 1.0 mils</td> <td>Cu, 0.8 mils</td> </tr> <tr> <td>WSON</td> <td>Au, 1.0 or 1.3 mils</td> <td>Cu, 0.8 or 1.0 mils</td> </tr> </tbody> </table>		Pkg Family	Current Wire	Additional Wire	SOIC	Au, 0.9 or 1.0 mils	Cu, 0.96 mils	SOT	Au, 0.6, 0.9 or 1.0 mils	Cu, 0.96 or 1.0 mils	TSSOP	Au, 1.0 mils	Cu, 0.96 mils	VSSOP	Au, 1.0 or 1.3 mils	Cu, 0.96 or 1.3 mils	WQFN	Au, 1.0 mils	Cu, 0.8 mils	WSON	Au, 1.0 or 1.3 mils	Cu, 0.8 or 1.0 mils			
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SOIC	Au, 0.9 or 1.0 mils	Cu, 0.96 mils																								
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VSSOP	Au, 1.0 or 1.3 mils	Cu, 0.96 or 1.3 mils																								
WQFN	Au, 1.0 mils	Cu, 0.8 mils																								
WSON	Au, 1.0 or 1.3 mils	Cu, 0.8 or 1.0 mils																								
Reason for Change:																										
Continuity of supply. 1) To align with world technology trends and use wiring with enhanced mechanical and electrical properties 2) Maximize flexibility within our Assembly/Test production sites. 3) Cu is easier to obtain and stock																										
Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):																										
None																										
Anticipated impact on Material Declaration																										
<input type="checkbox"/>	No Impact to the Material Declaration	<input checked="" type="checkbox"/>	Material Declarations or Product Content reports are driven from production data and will be available following the production release. Upon production release the revised reports can be obtained from the TI ECO website .																							
Changes to product identification resulting from this PCN:																										
None																										

Product Affected:

Device	Pkg Family	Device	Pkg Family
LDC83L37ACME/NOPB	SOIC	SN74LVC2G14DBVRG4	SOT
LDC83L37ACMX/NOPB	SOIC	SN74LVC2G14DBVTG4	SOT
LF356M	SOIC	SN74LVC2G17DBV3	SOT
LF356M/NOPB	SOIC	SN74LVC2G17DBVRE4	SOT
LM2931AM-5.0	SOIC	SN74LVC2G17DBVTG4	SOT
LM2931AM-5.0/NOPB	SOIC	SN74LVC2G34DBV3	SOT
LM2931AMX-5.0/NOPB	SOIC	SN74LVC2G34DBVRE4	SOT
LM2931AMX-5.0/SL162905	SOIC	SN74LVC2G34DBVRG4	SOT
LM2931CM	SOIC	SN74LVC2G34DBVTG4	SOT
LM2931CM/NOPB	SOIC	SN74LVC2GU04DBV3	SOT
LM2931CMX	SOIC	SN74LVC2GU04DBVR	SOT
LM2931CMX/NOPB	SOIC	SN74LVC2GU04DBVT	SOT
LM2931CMX/SL162913	SOIC	TLV341AIDBVR	SOT
LM2931M-5.0	SOIC	TLV341AIDBVT	SOT
LM2931M-5.0/NOPB	SOIC	TLV341AIDBVTE4	SOT
LM2931MX-5.0	SOIC	TLV341IDBVR	SOT
LM2931MX-5.0/NOPB	SOIC	TLV341IDBVRG4	SOT
LM2936BM-3.3/NOPB	SOIC	TS5A3157DBVR	SOT
LM2936BM-5.0/NOPB	SOIC	TS5A3157DBVRG4	SOT
LM2936BMX-3.3/NOPB	SOIC	TS5A3159ADBVR	SOT
LM2936BMX-5.0/NOPB	SOIC	TS5A3159ADBVRE4	SOT
LM2936HVBMA-3.3	SOIC	TS5A3159ADBVRG4	SOT
LM2936HVBMA-3.3/NOPB	SOIC	TS5A3159ADBVT	SOT
LM2936HVBMA-5.0	SOIC	TS5A3159ADBVTE4	SOT
LM2936HVBMA-5.0/NOPB	SOIC	TS5A3159ADBVTG4	SOT
LM2936HVBMAX3.3	SOIC	TS5A3159DBVR	SOT
LM2936HVBMAX3.3/NOPB	SOIC	TS5A3159DBVRE4	SOT
LM2936HVBMAX5.0/NOPB	SOIC	TS5A3159DBVRG4	SOT
LM2936HVMA-5.0	SOIC	TS5A3159DBVT	SOT
LM2936HVMA-5.0/NOPB	SOIC	TS5A3159DBVTE4	SOT
LM2936HVMAX-5.0	SOIC	TS5A3159DBVTG4	SOT
LM2936HVMAX-5.0/NOPB	SOIC	TS5A3160DBVR	SOT
LM2936M-3.0/NOPB	SOIC	TS5A3160DBVT	SOT
LM2936M-3.3	SOIC	TS5A3160DBVTE4	SOT
LM2936M-3.3/NOPB	SOIC	TS5A3160DBVTG4	SOT
LM2936M-5.0	SOIC	TS5A63157DBVRG4	SOT

LM2936M-5.0/NOPB	SOIC	TXB0101DBVR	SOT
LM2936M-5.0/SL162643	SOIC	TXB0101DBVRG4	SOT
LM2936MX-3.3/NOPB	SOIC	TXB0101DBVT	SOT
LM2936MX-5.0	SOIC	TXB0101DBVTG4	SOT
LM2936MX-5.0/E7002701	SOIC	TXS0101DBVR	SOT
LM2936MX-5.0/NAK1	SOIC	TXS0101DBVRG4	SOT
LM2936MX-5.0/NOPB	SOIC	TXS0101DBVT	SOT
LM2936MX-5.0/SL110245	SOIC	TXS0101DBVTG4	SOT
LM5002MA/NOPB	SOIC	CB0183MTAX/NOPB	TSSOP
LM9036M-3.3/NOPB	SOIC	CB0183MTAX/S7001278	TSSOP
LM9036M-5.0	SOIC	LDC3434MTE/NOPB	TSSOP
LM9036M-5.0/NOPB	SOIC	LDC3434MTX/NOPB	TSSOP
LM9036MX-3.3/NAK2	SOIC	LM25037MT/NOPB	TSSOP
LM9036MX-3.3/NOPB	SOIC	LM25037MTX/NOPB	TSSOP
LM9036MX-5.0/NAK1	SOIC	LM25115AMT/NOPB	TSSOP
LM9036MX-5.0/NOPB	SOIC	LM25115AMTX/NOPB	TSSOP
LM9076BMA-3.3/NOPB	SOIC	LM2647MTC/NOPB	TSSOP
LM9076BMA-5.0	SOIC	LM2647MTCX/NOPB	TSSOP
LM9076BMA-5.0/NOPB	SOIC	LM2657MTC/NOPB	TSSOP
LM9076BMAX-3.3/NOPB	SOIC	LM2657MTCX/NOPB	TSSOP
LM9076BMAX-5.0/NAK2	SOIC	LM2742MTCX/NOPB	TSSOP
LM9076BMAX-5.0/NOPB	SOIC	LM2743MTC	TSSOP
LMB1024MX-1/E7001820	SOIC	LM2743MTC/NOPB	TSSOP
LMC6494BEM	SOIC	LM2743MTCX/NOPB	TSSOP
LP2952AIM	SOIC	LM2744MTC/NOPB	TSSOP
LP2952AIM/NOPB	SOIC	LM2744MTCX/NOPB	TSSOP
LP2952AIMX/NOPB	SOIC	LM2745MTC/NOPB	TSSOP
LP2952IM	SOIC	LM2745MTCX/NOPB	TSSOP
LP2952IM/NOPB	SOIC	LM2747MTC/NOPB	TSSOP
LP2952IMX/NOPB	SOIC	LM2747MTCX/NOPB	TSSOP
LP2953AIM/NOPB	SOIC	LM2748MTCX/NOPB	TSSOP
LP2953AIMX/NOPB	SOIC	LM5025AMTC/NOPB	TSSOP
LP2953IM	SOIC	LM5025AMTCX/NOPB	TSSOP
LP2953IM/NOPB	SOIC	LM5025BMTC/NOPB	TSSOP
LP2953IMX/NOPB	SOIC	LM5025BMTCX/NOPB	TSSOP
SM73402MA/NOPB	SOIC	LM5025CMTC/NOPB	TSSOP
SM73402MAE/NOPB	SOIC	LM5025CMTCE/NOPB	TSSOP
SM73402MAX/NOPB	SOIC	LM5025CMTCX/NOPB	TSSOP
TPS92074D	SOIC	LM5025MTC/NOPB	TSSOP
TPS92074DR	SOIC	LM5025MTCX/NOPB	TSSOP
TPS92075D/NOPB	SOIC	LM5026MT	TSSOP
TPS92075DR/NOPB	SOIC	LM5026MT/NOPB	TSSOP
EMB1424MFE/NOPB	SOT	LM5026MTX/NOPB	TSSOP
EMB1441MFE/NOPB	SOT	LM5041BMTC/NOPB	TSSOP

EMB1441MFX/NOPB	SOT	LM5041BMTCX/NOPB	TSSOP
LDC3517AIM5/NOPB	SOT	LM5041MTC/NOPB	TSSOP
LM2664M6	SOT	LM5041MTCX/NOPB	TSSOP
LM2664M6/NOPB	SOT	LM5071MT-50/NOPB	TSSOP
LM2664M6X	SOT	LM5071MT-80/NOPB	TSSOP
LM2664M6X/NOPB	SOT	LM5071MTX-50/NOPB	TSSOP
LM2665M6	SOT	LM5071MTX-80/NOPB	TSSOP
LM2665M6/NOPB	SOT	LM5115AMT/NOPB	TSSOP
LM2665M6X	SOT	LM5115AMTX/NOPB	TSSOP
LM2665M6X/NOPB	SOT	LMH0026MH/NOPB	TSSOP
LM2681M6/NOPB	SOT	SM72445MTE/NOPB	TSSOP
LM2681M6X	SOT	ADC141S628CIMM/NOPB	VSSOP
LM2681M6X/NOPB	SOT	ADC141S628CIMMX/NOPB	VSSOP
LM2765M6X/NOPB	SOT	LM2660MM	VSSOP
LM2766M6/NOPB	SOT	LM2660MM/NOPB	VSSOP
LM2766M6X/NOPB	SOT	LMV875MM/NOPB	VSSOP
LM2767M5	SOT	LMV875MMX/NOPB	VSSOP
LM2767M5/NOPB	SOT	LMV876MM/NOPB	VSSOP
LM2767M5X/NOPB	SOT	LMV876MMX/NOPB	VSSOP
LM3420AM5-8.4/NOPB	SOT	LDC4029MM/NOPB	VSSOP
LM3420M5X-8.4/NOPB	SOT	LDC4029MME/NOPB	VSSOP
LM4041CIM7-1.2/NOPB	SOT	LDC4029MMX/NOPB	VSSOP
LM828M5	SOT	LM25007MM	VSSOP
LM828M5/NOPB	SOT	LM25007MM/NOPB	VSSOP
LM828M5X	SOT	LM25007MMX/NOPB	VSSOP
LM828M5X/NOPB	SOT	LM2622MM-ADJ/NOPB	VSSOP
LMV116MF/NOPB	SOT	LM2622MMX-ADJ/NOPB	VSSOP
LMV116MFX/NOPB	SOT	LM2622MMX-ADJ/S7000470	VSSOP
LMV118MF/NOPB	SOT	LM2682MM/NOPB	VSSOP
LMV118MFX/NOPB	SOT	LM2682MMX/NOPB	VSSOP
LP2985IM5X-3.3/S7002284	SOT	LM2698MM-ADJ/NOPB	VSSOP
LP5907MFX-1.2/NOPB	SOT	LM2698MMX-ADJ/NOPB	VSSOP
LP5907MFX-1.5/NOPB	SOT	LM3444MM/NOPB	VSSOP
LP5907MFX-1.8/NOPB	SOT	LM3444MM/S7002725	VSSOP
LP5907MFX-2.5/NOPB	SOT	LM3444MMX/NOPB	VSSOP
LP5907MFX-2.8/NOPB	SOT	LM3444MMX/S7002724	VSSOP
LP5907MFX-2.85/NOPB	SOT	LM3445MM/NOPB	VSSOP
LP5907MFX-3.0/NOPB	SOT	LM3445MM/S7002547	VSSOP
LP5907MFX-3.1/NOPB	SOT	LM3445MMX/NOPB	VSSOP
LP5907MFX-3.2/NOPB	SOT	LM3445MMX/S7002546	VSSOP
LP5907MFX-3.3/NOPB	SOT	LM3497MM/NOPB	VSSOP
LP5907MFX-4.5/NOPB	SOT	LM3497MM/S7002611	VSSOP
74AUC2GU04DBVRG4	SOT	LM3497MMX/NOPB	VSSOP
74AVCH1T45DBVRE4	SOT	LM3497MMX/S7002539	VSSOP

74AVCH1T45DBVRG4	SOT	LM5007MM	VSSOP
74AVCH1T45DBVTG4	SOT	LM5007MM/NOPB	VSSOP
74LVC1G10DBVRG4	SOT	LM5007MMX/NOPB	VSSOP
74LVC1G175DBVRE4	SOT	DS100MB201SQ/NOPB	WQFN
74LVC1G175DBVRG4	SOT	DS100MB201SQE/NOPB	WQFN
74LVC1G175DBVTG4	SOT	DS22EV5110SQ/NOPB	WQFN
74LVC1G3157DBVRE4	SOT	DS22EV5110SQE/NOPB	WQFN
74LVC1G3157DBVRG4	SOT	DS22EV5110SQX/NOPB	WQFN
74LVC1G3208DBVRE4	SOT	DS32EL0124SQ/NOPB	WQFN
74LVC1G3208DBVRG4	SOT	DS32EL0124SQE/NOPB	WQFN
74LVC1G3208DBVTG4	SOT	DS32EL0124SQX/NOPB	WQFN
74LVC1G332DBVRG4	SOT	DS32EL0421SQ/NOPB	WQFN
74LVC1G373DBVRE4	SOT	DS32EL0421SQE/NOPB	WQFN
74LVC1GX04DBVTG4	SOT	DS32EL0421SQX/NOPB	WQFN
74LVC2GU04DBVRG4	SOT	DS32ELX0124SQE/NOPB	WQFN
74LVC2GU04DBVTE4	SOT	DS32ELX0124SQX/NOPB	WQFN
LMV341IDBVR	SOT	DS32ELX0421SQE/NOPB	WQFN
LMV341IDBVRE4	SOT	DS34RT5110SQ/NOPB	WQFN
LMV341IDBVRG4	SOT	DS34RT5110SQE/NOPB	WQFN
SN74AUC1G19DBVR	SOT	DS34RT5110SQX/NOPB	WQFN
SN74AUC1G19DBVT	SOT	DS42BR400TSQ/NOPB	WQFN
SN74AUC2G04DBVR	SOT	DS50PCI401SQ/NOPB	WQFN
SN74AUC2G04DBVT	SOT	DS50PCI401SQE/NOPB	WQFN
SN74AUC2G06DBVR	SOT	DS50PCI402SQ/NOPB	WQFN
SN74AUC2G06DBVT	SOT	DS50PCI402SQE/NOPB	WQFN
SN74AUC2G07DBVT	SOT	DS64BR401SQ/NOPB	WQFN
SN74AUC2G34DBVR	SOT	DS64BR401SQE/NOPB	WQFN
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SN74AUC2GU04DBVR	SOT	DS64MB201SQE/NOPB	WQFN
SN74AUC2GU04DBVT	SOT	DS90C185SQX/NOPB	WQFN
SN74AUP1G57DBVR	SOT	LM10515SQE-B/NOPB	WQFN
SN74AUP1G57DBVT	SOT	LM10515SQX-B/NOPB	WQFN
SN74AUP1G58DBVR	SOT	LM4308SQ/NOPB	WQFN
SN74AUP1G58DBVT	SOT	LM5035BSQ/NOPB	WQFN
SN74AUP1G97DBVT	SOT	LM5035SQ/NOPB	WQFN
SN74AUP1G97DBVTG4	SOT	LM8333FLQ8X/NOPB	WQFN
SN74AUP1G98DBVR	SOT	LM8333FLQ8Y/NOPB	WQFN
SN74AUP1G98DBVT	SOT	LMH0040SQE/NOPB	WQFN
SN74AUP1T57DBVR	SOT	LMH0040SQX/NOPB	WQFN
SN74AUP1T57DBVT	SOT	LMH0041SQ/NOPB	WQFN
SN74AUP1T58DBVR	SOT	LMH0041SQE/NOPB	WQFN
SN74AUP1T97DBVR	SOT	LMH0041SQX/NOPB	WQFN
SN74AUP1T97DBVT	SOT	LMH0050SQE/NOPB	WQFN
SN74AUP1T97DBVTG4	SOT	LMH0051SQE/NOPB	WQFN

SN74AUP1T98DBVR	SOT	LMH0070SQ/NOPB	WQFN
SN74AUP1T98DBVT	SOT	LMH0070SQE/NOPB	WQFN
SN74AVC1T45DBVR	SOT	LMH0071SQ/NOPB	WQFN
SN74AVC1T45DBVRE4	SOT	LMH0071SQE/NOPB	WQFN
SN74AVC1T45DBVRG4	SOT	LMH0340SQ/NOPB	WQFN
SN74AVC1T45DBVT	SOT	LMH0340SQE/NOPB	WQFN
SN74AVC1T45DBVTE4	SOT	LMH0340SQX/NOPB	WQFN
SN74AVC1T45DBVTG4	SOT	LMH0341SQ/NOPB	WQFN
SN74AVCH1T45DBVR	SOT	LMH0341SQE/NOPB	WQFN
SN74AVCH1T45DBVT	SOT	LMH0341SQX/NOPB	WQFN
SN74LVC1G0832DBVR	SOT	LMP93601NHZR	WQFN
SN74LVC1G0832DBVT	SOT	LMP93601NHZT	WQFN
SN74LVC1G10DBVR	SOT	LMX2581ESQE/NOPB	WQFN
SN74LVC1G10DBVT	SOT	LMX2581ESQX/NOPB	WQFN
SN74LVC1G11DBVR	SOT	LP8556SQ-E00/NOPB	WQFN
SN74LVC1G11DBVRE4	SOT	LP8556SQ-E08/NOPB	WQFN
SN74LVC1G11DBVRG4	SOT	LP8556SQ-E09/NOPB	WQFN
SN74LVC1G11DBVT	SOT	LP8556SQE-E00/NOPB	WQFN
SN74LVC1G175DBVR	SOT	LP8556SQE-E08/NOPB	WQFN
SN74LVC1G175DBVT	SOT	LP8556SQE-E09/NOPB	WQFN
SN74LVC1G18DBV3	SOT	LP8556SQX-E00/NOPB	WQFN
SN74LVC1G18DBVR	SOT	LP8556SQX-E08/NOPB	WQFN
SN74LVC1G18DBVRG4	SOT	LP8556SQX-E09/NOPB	WQFN
SN74LVC1G19DBVR	SOT	LP8565A10ARWCR	WQFN
SN74LVC1G19DBVRE4	SOT	LP8565A10ARWCT	WQFN
SN74LVC1G19DBVRG4	SOT	EQ50F100LR/NOPB	WSON
SN74LVC1G19DBVT	SOT	LDC1000NHRJ	WSON
SN74LVC1G27DBVRE4	SOT	LDC1000NHRR	WSON
SN74LVC1G3157DBV3	SOT	LDC1000NHRT	WSON
SN74LVC1G3157DBVT	SOT	LDC1041NHRJ	WSON
SN74LVC1G3208DBVR	SOT	LDC1041NHRR	WSON
SN74LVC1G3208DBVT	SOT	LDC1041NHRT	WSON
SN74LVC1G373DBVR	SOT	LDC1051NHRJ	WSON
SN74LVC1G374DBVR	SOT	LDC1051NHRR	WSON
SN74LVC1G386DBVR	SOT	LDC1051NHRT	WSON
SN74LVC1G57DBVR	SOT	LM25085ASD/NOPB	WSON
SN74LVC1G57DBVRG4	SOT	LM25085ASDE/NOPB	WSON
SN74LVC1G58DBVR	SOT	LM25085SD/NOPB	WSON
SN74LVC1G58DBVRG4	SOT	LM25085SDE/NOPB	WSON
SN74LVC1G97DBV3	SOT	LM25101ASD/NOPB	WSON
SN74LVC1G97DBVR	SOT	LM25101ASDX-1/NOPB	WSON
SN74LVC1G97DBVRE4	SOT	LM25101BSD/NOPB	WSON
SN74LVC1G97DBVRG4	SOT	LM25101BSDX/NOPB	WSON
SN74LVC1G97DBVT	SOT	LM25101CSDX/NOPB	WSON

SN74LVC1G97DBVTG4	SOT	LM5001SD/NOPB	WSON
SN74LVC1G98DBV3	SOT	LM5001SDE/NOPB	WSON
SN74LVC1G98DBVR	SOT	LM5002SD/NOPB	WSON
SN74LVC1G98DBVRG4	SOT	LM5026SD/NOPB	WSON
SN74LVC1G98DBVT	SOT	LM5026SDX/NOPB	WSON
SN74LVC1G98DBVTG4	SOT	LM5085SD/NOPB	WSON
SN74LVC1GX04DBVR	SOT	LM5085SDE/NOPB	WSON
SN74LVC1GX04DBVT	SOT	LM5101BSD/NOPB	WSON
SN74LVC1T45DBVR	SOT	LM5101BSDX/NOPB	WSON
SN74LVC1T45DBVRE4	SOT	LM5101CSD/NOPB	WSON
SN74LVC1T45DBVRG4	SOT	LM5109ASD/NOPB	WSON
SN74LVC1T45DBVT	SOT	LM5109BSD/NOPB	WSON
SN74LVC1T45DBVTG4	SOT	LMH2180SD/NOPB	WSON
SN74LVC2G04DBV3	SOT	LMH2180SDE/NOPB	WSON
SN74LVC2G04DBVRE4	SOT	LMH2180YD/NOPB	WSON
SN74LVC2G04DBVRG4	SOT	LMV221SD/NOPB	WSON
SN74LVC2G04DBVTG4	SOT	LMV221SDX/NOPB	WSON
SN74LVC2G06DBV3	SOT	LMV221SDX/S7002595	WSON
SN74LVC2G06DBVR	SOT	LMV225SD/NOPB	WSON
SN74LVC2G06DBVRE4	SOT	LMV225SDX/NOPB	WSON
SN74LVC2G06DBVRG4	SOT	LMV228SD/NOPB	WSON
SN74LVC2G07DBV3	SOT	LMV875DSCR	WSON
SN74LVC2G07DBVRE4	SOT	LMV875DSCT	WSON
SN74LVC2G07DBVRG4	SOT	LP3879SD-1.2/J7002447	WSON
SN74LVC2G07DBVT	SOT	LP3879SD-1.2/NOPB	WSON
SN74LVC2G14DBV3	SOT	SM74104SD/NOPB	WSON
SN74LVC2G14DBVRE4	SOT	SN1410001DSSR	WSON

Qualification Report

0.96 mil Cu wire qual for SOT23 Packages

Product Attributes

Attributes	Qual Device: LM4041AIM3-1.2	Qual Device: LP3985IM5X-5.0	Qual Device: LMC7101AIM5NOPB	Qual Device: LM431CCM3NOPB
Assembly Site	TIEMA	TIEMA	TIEMA	TIEMA
Package Family	SOT	SOT	SOT	SOT
Flammability Rating	UL 94 V-0	UL 94 V-0	UL 94 V-0	UL 94 V-0
Wafer Fab Supplier	GFAB	MFAB	GFAB	GFAB
Wafer Fab Process	BPLFAST-1	CMOS7	P2CMOS	SLM

Qualification Results

Data Displayed as: Number of lots / Total sample size /
Total failed

Type	Test Name / Condition	Duration	Qual Device: LM4041 AIM3-1.2	Qual Device: LP3985IM5X-5.0	Qual Device: LMC7101AIM5NOPB	Qual Device: LM431CCM3NOPB
PC	PreCon Level 1	Level 1-260C	3/693/0	3/462/0	3/693/0	3/462/0
HAST	Biased HAST, 130C/85%RH	96/hrs. @130C	3/231/0	-	3/231/0	-
AC	Autoclave 121C	96HRS	3/231/0	3/231/0	3/231/0	3/231/0
TC	Temperature Cycle, -65/150C	TMCL500X	3/231/0	3/231/0	3/231/0	3/231/0
HTSL	High Temp Storage Bake 150C	1000 hrs. @150C	1/77/0	-	1/77/0	1/77/0
MQ	Manufacturability (Assembly)	(per mfg. Site specification)	Pass	Pass	Pass	Pass
DPA	Destructive Physical Analysis Post 500 Temp Cycle	x-section and de process to examine assembly robustness, Check for stich bond and bond pad integrity	3/15/0	3/15/0	3/15/0	3/15/0
YLD	FTY and Bin Summary	Compare against baseline	Pass	Pass	Pass	Pass

Qualification Report

0.96 mil Cu wire qual for SOIC Packages

Product Attributes

Attributes	Qual Device: DS90CP22MXA1CL	Qual Device: LMV324MX	Qual Device: LP2995MXNOPB	Qual Device: LMC6482AIM/NOPB
Assembly Site	TIEMA	TIEMA	TIEMA	TIEMA
Package Family	SOIC	SOIC	SOIC	SOIC
Flammability Rating	UL 94 V-0	UL 94 V-0	UL 94 V-0	UL 94 V-0
Wafer Fab Supplier	MFAB	MFAB	MFAB	GFAB
Wafer Fab Process	CMOS7	CS80	CS65	P2CMOS

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: DS90CP22MXA1CL	Qual Device: LMV324MX	Qual Device: LP2995MXNOPB	Qual Device: LMC6482AIM/NOPB
PC	PreCon Level 1	Level 1-260C	3/462/0	-	3/462/0	3/693/0

HAST	Biased HAST, 130C/85%RH	96/hrs. @130C	-	-	-	3/231/0
AC	Autoclave 121C	96HRS	3/231/0	-	3/231/0	3/231/0
TC	Temperature Cycle, -65/150C	TMCL500X	3/231/0	-	3/231/0	3/231/0
HTSL	High Temp Storage Bake 150C	1000 hrs. @150C	-	-	-	1/77/0
MQ	Manufacturability (Assembly)	(per mfg. Site specification)	-	Pass	Pass	Pass
DPA	Destructive Physical Analysis Post 500 Temp Cycle	x-section and de process to examine assembly robustness, Check for stich bond and bond pad integrity	3/15/0	-	3/15/0	3/15/0
YLD	FTY and Bin Summary	Compare against baseline	-	Pass	Pass	Pass

Qualification Report

0.96 mil Cu wire qual for VSSOP & TSSOP Packages

Product Attributes

Attributes	Qual Device: LMV852MMX	Qual Device: LMC6482IMM	Qual Device: LM93C1MT	Qual Device: LM5642MHX
Assembly Site	TIEMA	TIEMA	TIEMA	TIEMA
Package Family	VSSOP	VSSOP	TSSOP	TSSOP
Flammability Rating	UL 94 V-0	UL 94 V-0	UL 94 V-0	UL 94 V-0
Wafer Fab Supplier	MFAB	GFAB	MFAB	MFAB
Wafer Fab Process	CMOS7	P2CMOS	CMOS7	ABCD150

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: LMV852MMX	Qual Device: LMC6482IMM	Qual Device: LM93C1MT	Qual Device: LM5642MHX
PC	PreCon Level 1	Level 1-260C	3/462/0	3/462/0	-	3/231/0
PC	PreCon Level 2	Level 2-260C	-	-	3/693/0	-
HAST	Biased HAST, 130C/85%RH	96/hrs. @130C	-	-	3/231/0	-
AC	Autoclave 121C	96HRS	3/231/0	3/231/0	3/231/0	-

TC	Temperature Cycle, -65/150C	TMCL500X	3/231/0	3/231/0	3/231/0	3/231/0
HTSL	High Temp Storage Bake 150C	1000 hrs. @150C	-	-	1/77/0	-
MQ	Manufacturability (Assembly)	(per mfg. Site specification)	Pass	Pass	-	-
DPA	Destructive Physical Analysis Post 500 Temp Cycle	x-section and de process to examine assembly robustness, Check for stich bond and bond pad integrity	3/15/0	3/15/0	-	3/15/0
YLD	FTY and Bin Summary	Compare against baseline	Pass	Pass	-	-

Qualification Report

0.96 mil Cu wire qual for TSSOP Packages

Product Attributes

Attributes	Qual Device: LMH0346MH	Qual Device: LM5037MT	Qual Device: LM3657MH/NOPB	Qual Device: SCANSTA111MTX
Assembly Site	TIEMA	TIEMA	TIEMA	TIEMA
Package Family	TSSOP	TSSOP	TSSOP	TSSOP
Flammability Rating	UL 94 V-0	UL 94 V-0	UL 94 V-0	UL 94 V-0
Wafer Fab Supplier	MFAB	GFAB	MFAB	MFAB
Wafer Fab Process	BICMOS8B+	ABCD150	CMOS7	CMOS7

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: LMH0346MH	Qual Device: LM5037MT	Qual Device: LM3657MH/NOPB	Qual Device: SCANSTA111MTX
PC	PreCon Level 1	Level 1-260C	-	3/693/0	3/462/0	-
PC	PreCon Level 2	Level 2-260C	-	-	-	3/462/0
PC	PreCon Level 3	Level 3-260C	3/231/0	-	-	-
THBT	THBT 85C, 85%RH	1000/hrs. @85C	-	3/231/0	-	-
AC	Autoclave 121C	96HRS	-	3/231/0	3/231/0	3/231/0

TC	Temperature Cycle, -65/150C	TMCL500X	3/231/0	3/231/0	3/231/0	3/231/0
HTSL	High Temp Storage Bake 150C	1000 hrs. @150C	-	1/77/0	-	-
MQ	Manufacturability (Assembly)	(per mfg. Site specification)	Pass	Pass	Pass	Pass
DPA	Destructive Physical Analysis Post 500 Temp Cycle	x-section and de process to examine assembly robustness, Check for stich bond and bond pad integrity	3/15/0	3/15/0	3/15/0	3/15/0
YLD	FTY and Bin Summary	Compare against baseline	Pass	Pass	Pass	Pass

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
 - The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
 - The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles
- Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>
Green/Pb-free Status:
Qualified Pb-Free(SMT) and Green

Qualification Report

0.8 mils Cu wire qual on BC13, CMOS9T and CMOS7 in WQFN and WSON Packages

Approved 09/23/2014

Product Attributes

Attributes	Qual Device: DP83848T SQ	Qual Device: DS91M040TSQ AW2	Qual Device: DS100DX410EL 16	Qual Device: DS80PCI402A2TT	Qual Device: LMH0366SQENOPB	Qual Device: LMH0394SQ/NOPB
Assembly Site	TIEM-AT	TIEM-AT	TIEM-AT	TIEM-AT	TIEM-AT	TIEM-AT
Package Family	WQFN	WQFN	WQFN	WQFN	WQFN	QFN
Flammability Rating	UL 94 V-0	UL 94 V-0	UL 94 V-0	UL 94 V-0	UL 94 V-0	UL 94 V-0
Wafer Fab Supplier	MAINEFAB	MAINEFAB	MAINEFAB	MAINEFAB	MAINEFAB	MAINEFAB
Wafer Fab Process	CMOS9T	CMOS7	BICMOS13	BICMOS13	BICMOS13	BICMOS13

- QBS: Qual By Similarity
- Qual Device DS100DX410EL16 is qualified at LEVEL3-260C
- Qual Device DS80PCI402A2TT is qualified at LEVEL2-260C
- Qual Device LMH0366SQENOPB is qualified at LEVEL1-260C
- Qual Device LMH0394SQ/NOPB is qualified at -
- Qual Device LMH0394SQ/NOPB REV A is qualified at LEVEL3-260C

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: DP83848T SQ	Qual Device: DS91M040TS QAW	Qual Device: DS100DX410 EL16	Qual Device: DS80PCI402 A2TT	Qual Device: LMH0366SQEN OPB	Qual Device: LMH0394SQ/N OPB
PC	PreCon Level 1	Level 1-260C					3/720/0	
PC	PreCon Level 2	Level 2-260C	3/1079/0		-	3/720/0	-	-
PC	PreCon Level 3	Level 3-260C	-	1/255/0	3/720/0	-	-	3/231/0
HAST	Biased HAST, 130C/85%RH	96hrs. @130C	-	-	-	-	-	3/231/0
AC	Autoclave 121C	96HRS	3/231/0	1/77/0	3/231/0	3/231/0	3/231/0	-
UHAST	Unbiased HAST 130C/85%RH	unHAST-96 HRS/-	3/231/0	1/77/0	3/231/0	3/231/0	3/231/0	-
TC	Temperature Cycle, -65/150C	TMCL500X	3/231/0	1/77/0	3/231/0	3/231/0	3/231/0	-
HTSL	High Temp Storage Bake 170C	420 hrs. @170C	3/231/0	-	-	3/231/0	-	-
ED	Side By Side Electrical Characterization.	Per Datasheet Parameters	1/30/0	1/30/0	1/30/0	1/30/0	1/30/0	-
MQ	Manufacturability (Assembly)	(per mfg. Site specification)	Pass	Pass	Pass	Pass	Pass	Pass
MSL	Thermal Path Integrity	Level 2-260C	3/30/0	1/22/0	3/66/0	3/66/0	3/66/0	-
DPA	Destructive Physical Analysis Post 500 Temp Cycle	x-section and deprocess to examine assembly robustness, Check for stich bond and bond pad integrity	3/3/0	-	3/15/0	3/15/0	3/15/0	1/5/0 Post 96 hours HAST
YLD	FTY and Bin Summary	Compare against baseline	Pass	Pass	Pass	Pass	Pass	Pass

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours

- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green

Qualification Report
**1.3 mils PCC wire qualification on ABCD150 (GFAB - 8 inch) in VSSOP package at
TIEMA**
Approved 10/30/2015
Product Attributes

Attributes	Qual Device: LM2682MM/NOPB	Qual Device: LM3445MM/NOPB
Assembly Site	TIEMA	TIEMA
Package Family	VSSOP	VSSOP
Flammability Rating	UL 94 V-0	UL 94 V-0
Wafer Fab Site	GFAB 200MM	GFAB 200MM
Wafer Fab Process	ABCD150	ABCD150

- QBS: Qual By Similarity

- Qual Devices qualified at LEVEL1-260CG: LM2682MM/NOPB, LM3445MM/NOPB

Product Attributes
Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: LM2682MM/NOPB	Qual Device: LM3445MM/NOPB
AC	Autoclave 121C	96 Hours	3/231/0	3/231/0
TC	Temperature Cycle, - 65/150C	500 Cycles	3/231/0	3/231/0
WBS	Bond Shear	Ball Bond shear/Post Temp Cycle	3/15/0	3/15/0
WBP	Bond Pull	Post Temp Cycle	3/15/0	3/15/0
MQ	Manufacturability (Assembly)	(per mfg. Site specification)	Pass	Pass
VQR	Visual Quality Inspection	Post Temp Cycle	Pass	Pass

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours

- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green

Qualification Report

Qualification of SOT23 DBV 6p at HNT with Cu wire

Approve Date 13-Nov-2015

Updated 11/16/2015-Added QBS Data

Product Attributes

Attributes	Qual Device: LMV341DBVR	Qual Device: SN74AUC1G19DBVR	Qual Device: TS5A3159DBVR	QBS Package Reference: SN74AHC1G126DBVR	QBS Package Reference: SN74CBTLV1G125DBVR
Assembly Site	HANA (HNT)	HANA (HNT)	HANA (HNT)	HNT	HNT
Package Family	SOT	SOT	SOT	SOT	SOT
Flammability Rating	UL 94 V-0	UL 94 V-0	UL 94 V-0	TBD	UL 94 V-0
Wafer Fab Supplier	DFAB	FFAB	FFAB	SHE SFAB	FR-BIP-1
Wafer Process	50A21X3	ASLC10	ACTPI	EPIC1S1-SLM	ASL3C

- QBS: Qual By Similarity

- Qual Devices qualified at LEVEL1-260CG: LMV341DBVR, SN74AUC1G19DBVR, TS5A3159DBVR

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: LMV341DBVR	Qual Device: SN74AUC1G19DBVR	Qual Device: TS5A3159DBVR	QBS Package Reference: SN74AHC1G126DBVR	QBS Package Reference: SN74CBTLV1G125DBVR
AC	Autoclave 121C	96 Hours	3/231/0	3/231/0	3/231/0	3/231/0	1/77/0
HAST	Biased HAST, 130C/85%RH	96 Hours	-	-	-	-	-
HTSL	High Temp. StorageBake, 150C	1000 Hours	-	3/231/0	3/231/0	-	-
HTSL	High Temp. StorageBake, 170C	420 Hours	-	-	-	3/231/0	1/77/0
LI	Lead Fatigue	Leads	-	-	3/66/0	-	-
LI	Lead Pull to Destruction	Leads	-	-	3/66/0	-	-
PD	Physical Dimensions	--	-	-	3/15/0	-	-
SD	Surface Mount Solderability	Pb Free	-	-	3/66/0	-	-
TC	Temperature Cycle, -65/150C	500 Cycles	3/231/0	3/231/0	3/231/0	3/231/0	1/77/0

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours

- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

 Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

Qualification Report

Qualification of SOT23 DBV 6p at HNT with Cu wire

Approve Date 13-Nov-2015

Updated 11/16/2015-Added QBS Data

Product Attributes

Attributes	QBS Package Reference: SN74LVC1GU04DBVR	QBS Package Reference: TS12A4517DBVR	QBS Package Reference: TS321DBVT	QBS Package Reference: TS5A3166DBVR
Assembly Site	HNT	HNT	HNT	HNT
Package Family	SOT	SOT	SOT	SOT
Flammability Rating	UL 94 V-0	UL 94 V-0	UL 94 V-0	UL 94 V-0
Wafer Fab Supplier	FR-BIP-1	DL-LIN	SHE SFAB	FR-BIP-1
Wafer Process	ASL3C	LBC3S	J11	ASLC10

- QBS: Qual By Similarity

- Qual Devices qualified at LEVEL1-260CG: LMV341DBVR, SN74AUC1G19DBVR, TS5A3159DBVR

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	QBS Package Reference: SN74LVC1GU04DBVR	QBS Package Reference: TS12A4517DBVR	QBS Package Reference: TS321DBVT	QBS Package Reference: TS5A3166DBVR
AC	Autoclave 121C	96 Hours	3/231/0	-	3/231/0	1/77/0
HAST	Biased HAST, 130C/85%RH	96 Hours	3/240/0	-	-	-
HTSL	High Temp. StorageBake, 150C	1000 Hours	-	-	-	-
HTSL	High Temp. StorageBake, 170C	420 Hours	3/231/0	-	3/231/0	-
LI	Lead Fatigue	Leads	3/66/0	-	-	-
LI	Lead Pull to Destruction	Leads	3/66/0	-	-	-
PD	Physical Dimensions	--	3/9/0	-	-	-
SD	Surface Mount Solderability	Pb Free	3/66/0	-	-	-
TC	Temperature Cycle, -65/150C	500 Cycles	3/231/0	1/75/0	3/231/0	1/77/0

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours

- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Qualification Report

Cu Conversion for SN1410001DSSR

Approve Date 12-Nov-2015

Product Attributes

Package Attributes	Qual Device: SN1410001DSSR	QBS Product Reference: DRV8835DSS	QBS Package Reference: SH6966ACC0RGCRG4	QBS Package Reference: TP565633ARTER	QBS Package Reference: TP565633BRTER
Assembly Site	CLARK-AT	CLARK-AT	CLARK-AT	CLARK-AT	CLARK-AT
Package Family	WSON	WSON	QFN	WQFN	WQFN
Package Designator	DSS	DSS	RGC	RTE	RTE
Package Size (mils)	78.74 X 118.11	78.74 X 118.11	354.33 X 354.33	118.11 X 118.11	118.11 X 118.11
Body Thickness (mils)	29.53	29.53	35.43	29.53	29.53
Pin Count	12	12	64	16	16
Lead Frame Type	Cu	Cu	Cu	Cu	Cu
Lead Finish	NIPdAu	NIPdAu	NIPdAu	NIPdAu	NIPdAu
Bond Wire Composition	Cu	Cu	Cu	Cu	Cu
Bond Wire Diameter(mils)	1.0	1.0	1.15	1.0	1.0
Flammability Rating	UL 94 V-0	UL 94 V-0	UL 94 V-0	-	-

- QBS: Qual By Similarity

- Qual Device SN1410001DSSR is qualified at LEVEL2-260C

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: SN1410001DSSR	QBS Product Reference: DRV8835DSS	QBS Package Reference: SH6966ACC0RGCRG4	QBS Package Reference: TP565633ARTER	QBS Package Reference: TP565633BRTER
AC	Autoclave 121C	96 Hours	-	-	3/231/0	-	-
ED	Electrical Characterization	Per Datasheet Parameters	1/30/0	1/30/0	-	-	-
ELFR	Early Life Failure Rate, 140C	48 Hours	-	-	-	-	-
HAST	Biased HAST, 130C/85%RH	96 Hours	-	-	3/231/0	-	-
HBM	ESD - HBM	2000 V	-	1/3/0	-	-	-
CDM	ESD - CDM	1500 V	-	1/3/0	-	-	-
HTOL	Life Test, 125C	1000 Hours	-	-	3/231/0	-	-
HTOL	Life Test, 140C	480 Hours	-	-	-	-	-
HTSL	High Temp. Storage Bake, 170C	420 Hours	-	-	3/231/0	-	-
LU	Latch-up	(per JESD78)	-	2/12/0	-	-	-
PD	Physical Dimensions	--	-	-	3/15/0	-	-
SD	Solderability	8 Hours Steam Age	-	-	3/66/0	-	-
TC	Temperature Cycle, -65/150C	500 Cycles	1/77/0	2/154/0	3/231/0	1/77/0	2/154/0
TS	Thermal Shock, -65/150C	500 Cycles	-	-	3/231/0	-	-
WBP	Bond Pull	Wires	1/80/0	-	3/228/0	1/76/0	1/76/0
WBS	Ball Bond Shear	Wires	1/80/0	-	-	1/76/0	1/76/0
WBS	Bond Shear	Wires	-	-	3/228/0	-	-

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

- The following are equivalent HTOL options based on an activation energy of 0.7eV: 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

- The following are equivalent HTSL options based on an activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours

- The following are equivalent Temp Cycle options per JESD47: -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
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